

Title (en)

USE OF POLYAMIDE AS AN ENCAPSULATING MATERIAL FOR PHOTOVOLTAIC MODULES

Title (de)

VERWENDUNG VON POLYAMID ALS EINKAPSELUNGSMATERIAL FÜR PHOTOVOLTAISCHE MODULE

Title (fr)

UTILISATION DE POLYAMIDE COMME MATÉRIAU D'ENCAPSULATION POUR MODULES PHOTOVOLTAÏQUES

Publication

EP 2150987 A2 20100210 (DE)

Application

EP 08733261 A 20080508

Priority

- AT 2008000158 W 20080508
- AT 7342007 A 20070510
- AT 20872007 A 20071220

Abstract (en)

[origin: CA2681835A1] The invention relates to the use of a polymer composite (1, 1'), comprising a backing material (3, 3'), selected from the group made up of polyethylene terephthalate (PET), polyethylene naphthenate (PEN) and ethylene-tetrafluoroethylene copolymer (ETFE), and layers of nylon 12 (2, 2', 4, 4') adjacent to the backing material on both sides, for producing photovoltaic modules.

IPC 8 full level

H01L 31/048 (2006.01); **B32B 27/34** (2006.01)

CPC (source: EP KR US)

B32B 27/08 (2013.01 - EP US); **B32B 27/34** (2013.01 - KR); **H01L 31/048** (2013.01 - EP US); **H01L 31/0481** (2013.01 - EP US); **H01L 31/049** (2014.12 - EP US); **B32B 2377/00** (2013.01 - EP US); **Y02B 10/10** (2013.01 - EP US); **Y02E 10/50** (2013.01 - EP US); **Y10T 428/31562** (2015.04 - EP US); **Y10T 428/31565** (2015.04 - EP US); **Y10T 428/31681** (2015.04 - EP US); **Y10T 428/31736** (2015.04 - EP US); **Y10T 428/3175** (2015.04 - EP US); **Y10T 428/31786** (2015.04 - EP US)

Citation (third parties)

Third party :

US 5582653 A 19961210 - KATAOKA ICHIRO [JP], et al

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA MK RS

DOCDB simple family (publication)

AT 505186 A1 20081115; AR 066506 A1 20090826; AR 066507 A1 20090826; AR 079922 A1 20120229; AT 10898 U1 20091215; AT 10899 U1 20091215; AT 505199 A1 20081115; AT E515065 T1 20110715; BR PI0811286 A2 20150120; BR PI0811432 A2 20150804; BR PI0811432 A8 20151103; BR PI0811432 A8 20151124; CA 2681835 A1 20081120; CA 2684637 A1 20081120; CL 2008001370 A1 20080822; CL 2008001371 A1 20080822; CN 101669214 A 20100310; CN 101669214 B 20111214; CN 101715608 A 20100526; CY 1111856 T1 20151104; DK 2143148 T3 20111003; EP 2143148 A1 20100113; EP 2143148 B1 20110629; EP 2150987 A2 20100210; ES 2366685 T3 20111024; HR P20110691 T1 20111031; JP 2010527142 A 20100805; JP 2010528454 A 20100819; KR 20100014415 A 20100210; KR 20100014682 A 20100210; MX 2009009561 A 20090916; MX 2009010922 A 20091029; PE 20090085 A1 20090424; PE 20090122 A1 20090503; PL 2143148 T3 20111130; PT 2143148 E 20110906; RS 51813 B 20111231; RU 2009145717 A 20110620; RU 2009145726 A 20110620; RU 2438210 C2 20111227; RU 2444807 C2 20120310; SI 2143148 T1 20111028; US 2010059105 A1 20100311; US 2010119841 A1 20100513; US 8318316 B2 20121127; WO 2008138021 A2 20081120; WO 2008138021 A3 20090709; WO 2008138022 A1 20081120

DOCDB simple family (application)

AT 7342007 A 20070510; AR P080101969 A 20080509; AR P080101970 A 20080509; AR P110100153 A 20110118; AT 08733262 T 20080508; AT 2008000158 W 20080508; AT 2008000159 W 20080508; AT 20872007 A 20071220; AT 80422009 U 20090609; AT 80432009 U 20090609; BR PI0811286 A 20080508; BR PI0811432 A 20080508; CA 2681835 A 20080508; CA 2684637 A 20080508; CL 2008001370 A 20080509; CL 2008001371 A 20080509; CN 200880011812 A 20080508; CN 200880015438 A 20080508; CY 111100919 T 20110922; DK 08733262 T 20080508; EP 08733261 A 20080508; EP 08733262 A 20080508; ES 08733262 T 20080508; HR P20110691 T 20110927; JP 2010506770 A 20080508; JP 2010506771 A 20080508; KR 20097019275 A 20080508; KR 20097020405 A 20080508; MX 2009009561 A 20080508; MX 2009010922 A 20080508; PE 2008000817 A 20080509; PE 2008000818 A 20080509; PL 08733262 T 20080508; PT 08733262 T 20080508; RS P20110376 A 20080508; RU 2009145717 A 20080508; RU 2009145726 A 20080508; SI 200830369 T 20080508; US 59734608 A 20080508; US 59759708 A 20080508